



# 100% Material Declaration Data Sheet TQG144

PK126 (v1.2.1) October 19, 2006

Material Declaration Data Sheet

**Average Weight: 1.4 g**

Component	Substance Description	CAS# or Description	% of Component	Use in Product	Component Weight/ Substance Weight (in grams)	Component % of Total
<b>Silicon Die</b>					<b>0.0147</b>	<b>1.05%</b>
	Silicon	7440-21-3	100.00		0.0147	
<b>Die Attach Material</b>					<b>0.00224</b>	<b>0.16%</b>
	Silver	7440-22-4	78.00		0.0017472	
	Epoxy (EP)	Trade Secret	22.00		0.0004928	
<b>Mold Compound</b>					<b>1.10208</b>	<b>78.72%</b>
	Epoxy Resin (EP)	Trade Secret	9.00		0.0991872	
	Phenolic Resin	Trade Secret	7.00		0.0771456	
	Carbon Black	1333-86-4	0.50		0.0055104	
	Silica	60676-86-0	82.50		0.909216	
	Bismuth	7440-69-9	Max 1.00		0.0110208	
<b>Leadframe</b>					<b>0.26124</b>	<b>18.66%</b>
	Copper	7440-50-8	98.85		0.25823574	
	Chromium	7440-47-3	0.30		0.00078372	
	Tin	7440-31-5	0.25		0.0006531	
	Zinc	7440-66-6	0.60		0.00156744	
<b>Leadframe Plating</b>					<b>0.00112</b>	<b>0.08%</b>
	Silver	7440-22-4	100.00		0.00112	
<b>Bond Wire</b>					<b>0.00616</b>	<b>0.44%</b>
	Gold	7440-57-5	100.00		0.00616	
<b>Ext. Plating</b>					<b>0.01246</b>	<b>0.89%</b>
	Tin	7440-31-5	100.00		0.01246	

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1

## Revision History

The following table shows the revision history for this document.

Date	Revision	Revision
2/09/06	1.0	Initial release.
7/10/06	1.1	100% Material Declaration.
9/28/06	1.2	Updated component descriptions.
10/19/06	1.2.1	Editorial change; corrected typo in Substance Description.